



Lead Free Package and Finish

**Applications:**

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply(UPS)
- Power Factor Correction (PFC)

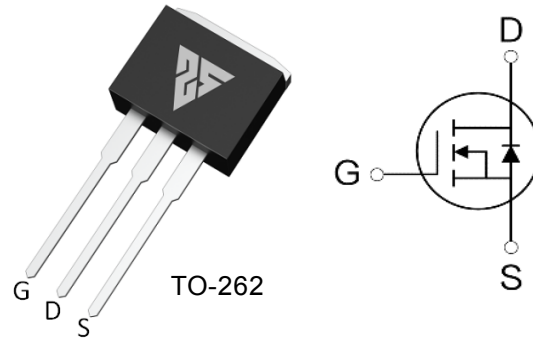
$I_D$	$R_{DS(ON)}(Typ)$	$V_{DSS}$
4A	2Ω	650V

**Features:**

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability

**Ordering Information**

Part Number	Package	Marking
RS4N65L	TO-262	RS4N65L



Not to Scale

**Absolute Maximum Ratings  $T_c=25$  unless otherwise specified**

Symbol	Parameter	RS4N65L	Units
$V_{DSS}$	Drain-to-Source Voltage	650	V
$I_D$	Continuous Drain Current	4	A
$I_{DM}$	Pulsed Drain Current (Note*1)	16	
PD	Power Dissipation	156	W
VGS	Gate-to-Source Voltage	±30	V
EAS	Single Pulse Avalanche Energy L=10mH VDD=50V RG=25Ω TJ=25	80	mJ
IAS	Avalanche Current (Note*1)	4	A
$E_{AR}$	Repetitive Avalanche Energy (Note*1)	0.32	mJ
TL TPKG	Maximum Temperature for Soldering	300 260	
	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds		
$T_J$ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

\* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" Table may cause permanent damage to the device.

**Thermal Resistance**

Symbol	Parameter	RS4N65L	Units	Test Conditions
$R_{\theta JC}$	Junction-to-Case	0.8	/ W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of +150
$R_{\theta JA}$	Junction-to-Ambient	62.5		1 cubic foot chamber, free air.

**OFF Characteristics**  $T_J=25^{\circ}\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-source Breakdown Voltage	650	--	--	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250 $\mu$ A
I <sub>DSS</sub>	Drain-to-Source Leakage Current	--	--	1.0	$\mu$ A	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	--	--	100	nA	V <sub>GS</sub> =30V, V <sub>DS</sub> =0V
	Gate-to-Source Reverse Leakage	--	--	-100		V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V

**ON Characteristics**  $T_J=25^{\circ}\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance (Note*2)	--	2	2.4	$\Omega$	V <sub>GS</sub> =10V, I <sub>D</sub> =2A
V <sub>GS(TH)</sub>	Gate Threshold Voltage	3.0	--	4.0	V	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250 $\mu$ A

**Resistive Switching Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
t <sub>d(ON)</sub>	Turn-on Delay Time	--	36	--	nS	V <sub>DS</sub> =325V I <sub>D</sub> =4A R <sub>G</sub> =25 $\Omega$
t <sub>rise</sub>	Rise Time	--	13	--		
t <sub>d(OFF)</sub>	Turn-OFF Delay Time	--	80	--		
t <sub>fall</sub>	Fall Time	--	24	--		

**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
C <sub>iss</sub>	Input Capacitance	--	543	--	pF	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=1.0MHz
C <sub>oss</sub>	Output Capacitance	--	53	--		
C <sub>rss</sub>	Reverse Transfer Capacitance	--	4.5	--		
Q <sub>g</sub>	Total Gate Charge	--	15	--	nC	V <sub>DS</sub> =520V I <sub>D</sub> =4A V <sub>GS</sub> =10V
Q <sub>gs</sub>	Gate-to-Source Charge	--	3	--		
Q <sub>gd</sub>	Gate-to-Drain("Miller") Charge	--	7	--		

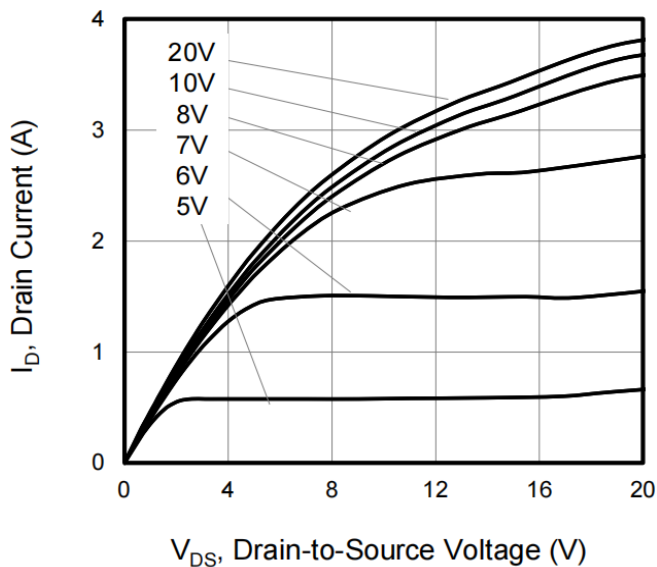
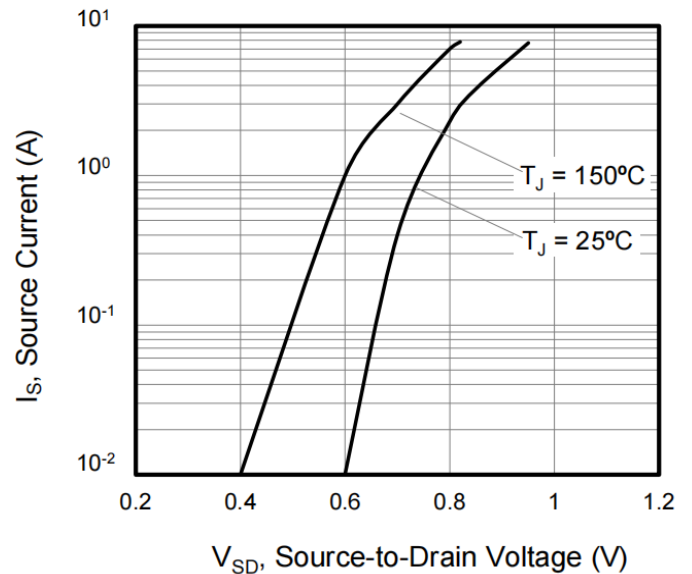
**Source-Drain Diode Characteristics**

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current	--	--	4	A	Integral pn-diode in MOSFET
I <sub>SM</sub>	Maximum Pulsed Current	--	--	16	A	
V <sub>SD</sub>	Diode Forward Voltage	--	--	1.4	V	I <sub>S</sub> =2A, V <sub>GS</sub> =0V
t <sub>rr</sub>	Reverse Recovery Time	--	550	--	nS	V <sub>GS</sub> =0V I <sub>S</sub> =2A, di/dt=100A/μs
Q <sub>rr</sub>	Reverse Recovery Charge	--	1.38	--	μC	

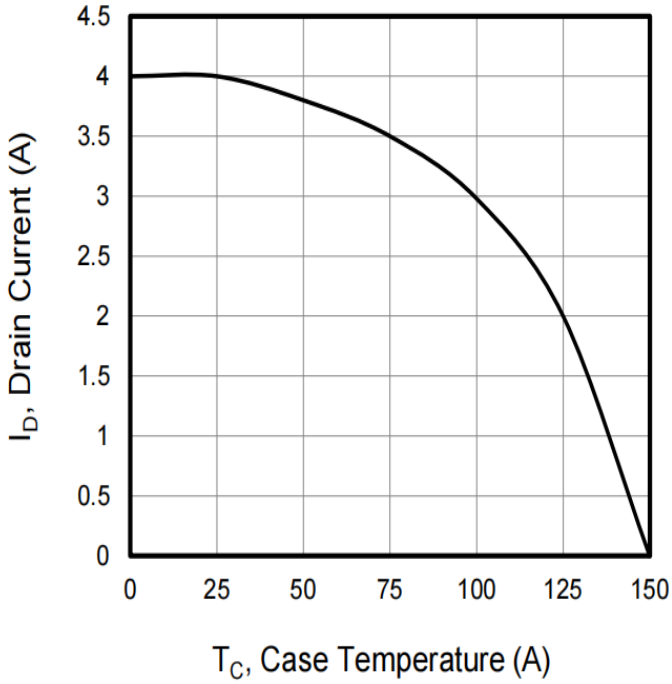
**Notes:**

\*1. Repetitive rating; pulse width limited by maximum junction temperature.

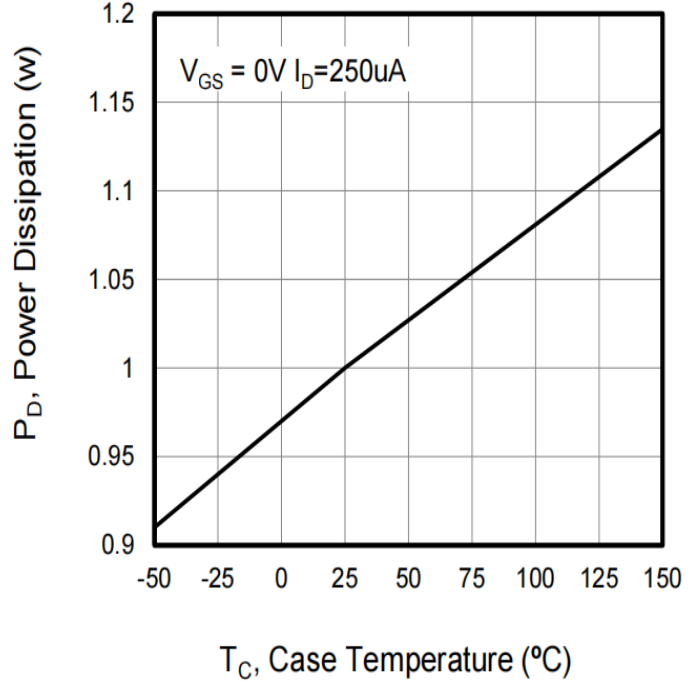
\*2. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

**Typical Feature curve**
**Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)**

**Figure 2. Body Diode Forward Voltage**


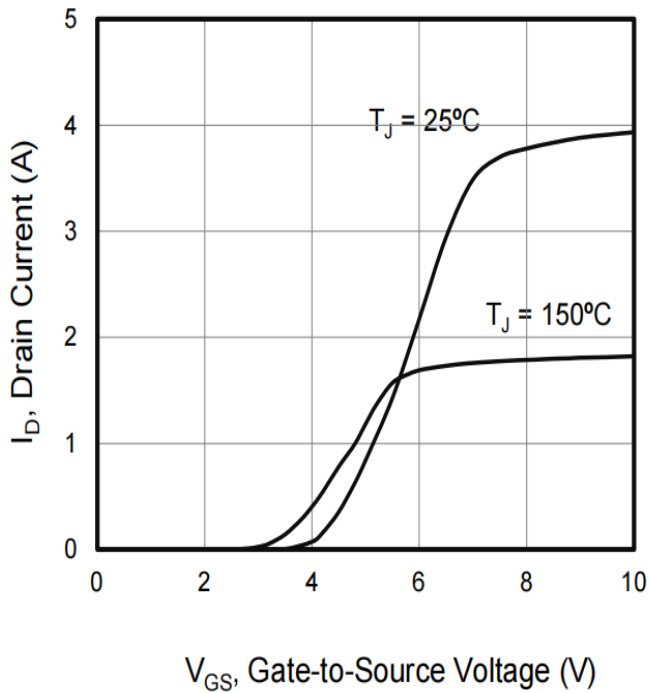
**Figure 3. Drain Current vs. Temperature**



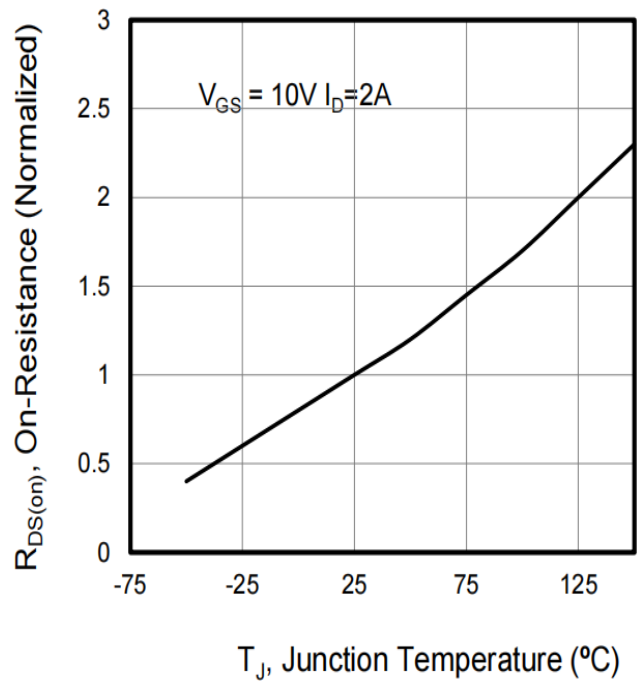
**Figure 4.  $BV_{DSS}$  Variation vs. Temperature**



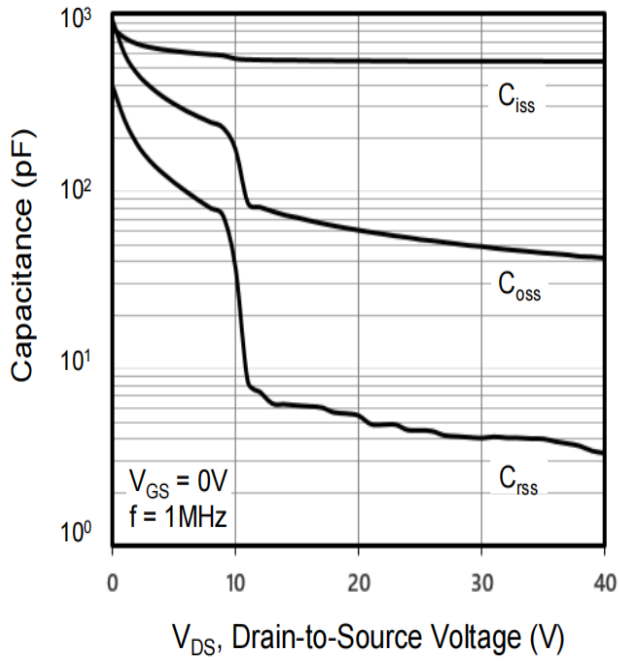
**Figure 5. Transfer Characteristics**



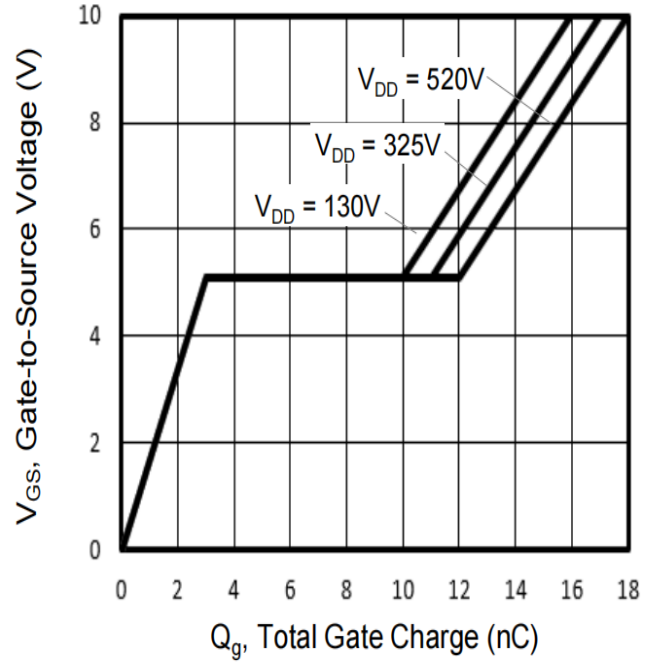
**Figure 6. On-Resistance vs. Temperature**



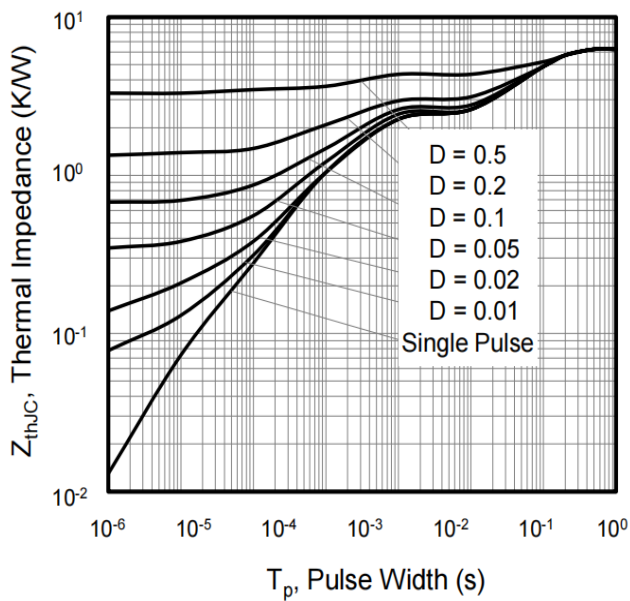
**Figure 7. Capacitance**



**Figure 8. Gate Charge**



**Figure 9. Transient Thermal Impedance**



**Test Circuits and Waveforms**

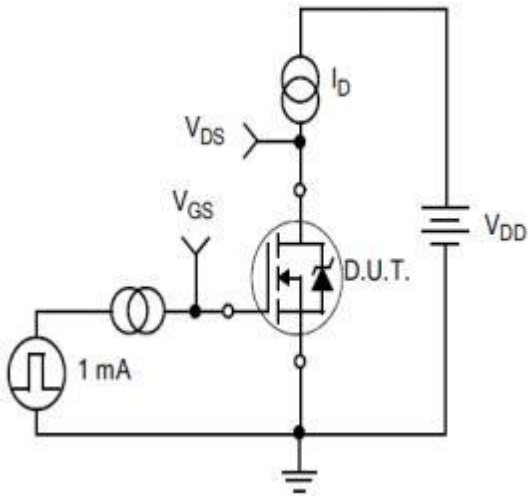


Figure12.  
Gate Charge Test Circuit

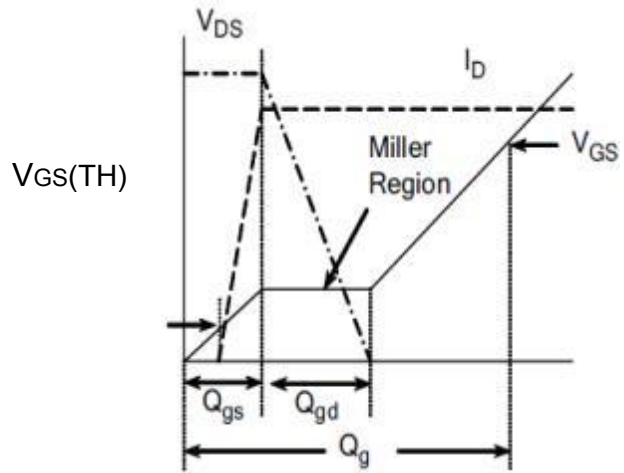


Figure13.  
Gate Charge Waveform

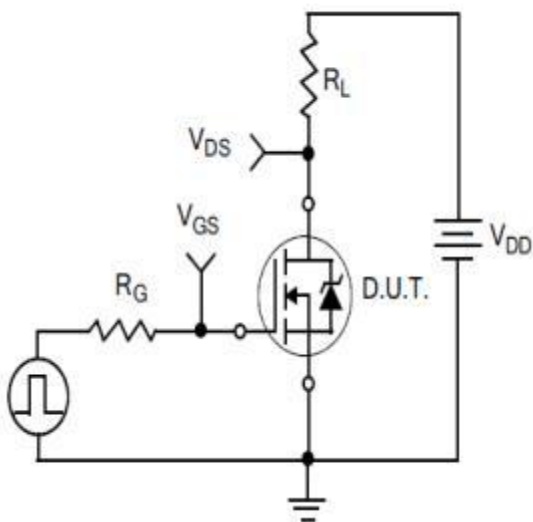


Figure14.  
Resistive Switching Test Circuit

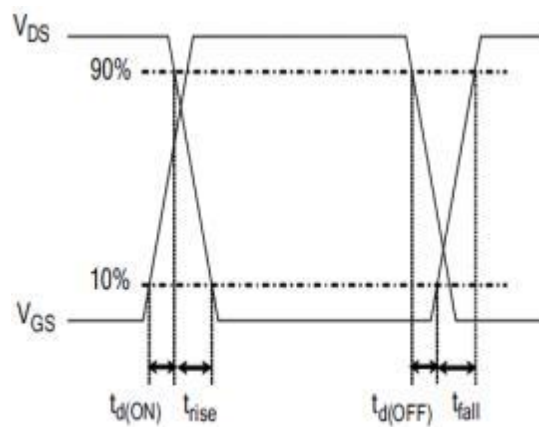


Figure15.  
Resistive Switching Waveforms

**Test Circuits and Waveforms**

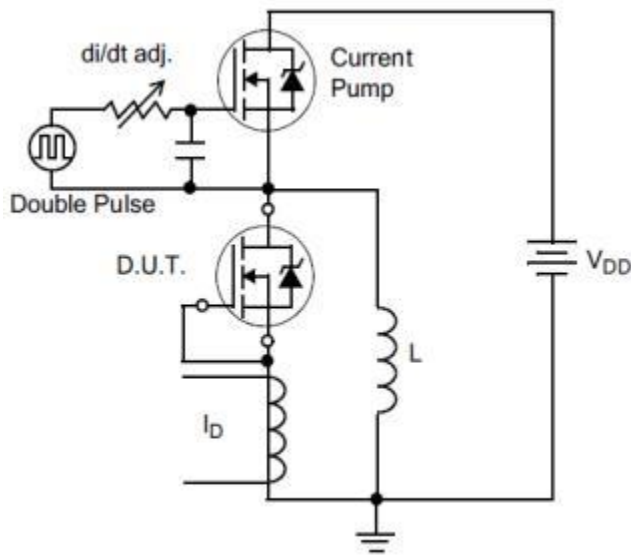


Figure16.Diode Reverse Recovery Test Circuit

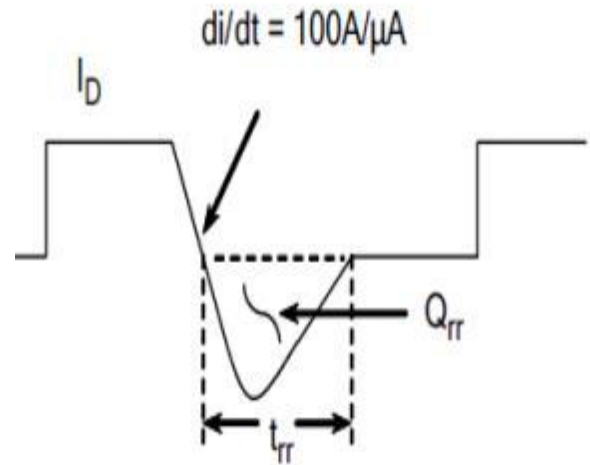


Figure17.Diode Reverse Recovery Waveform

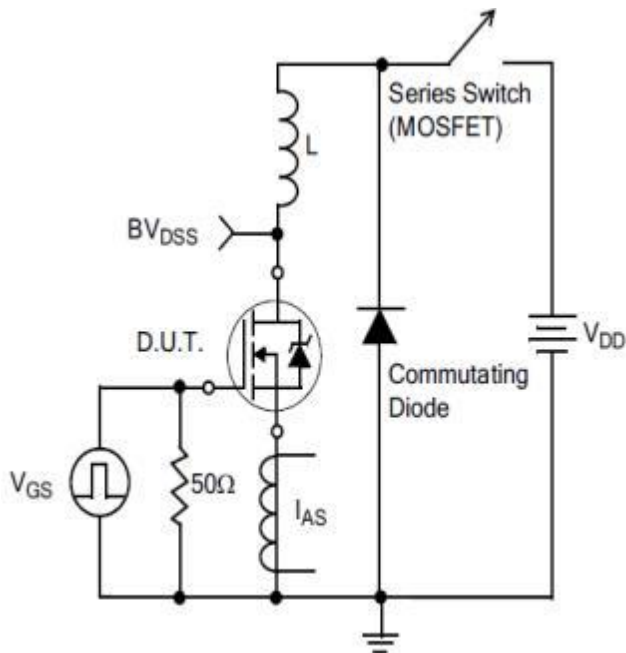
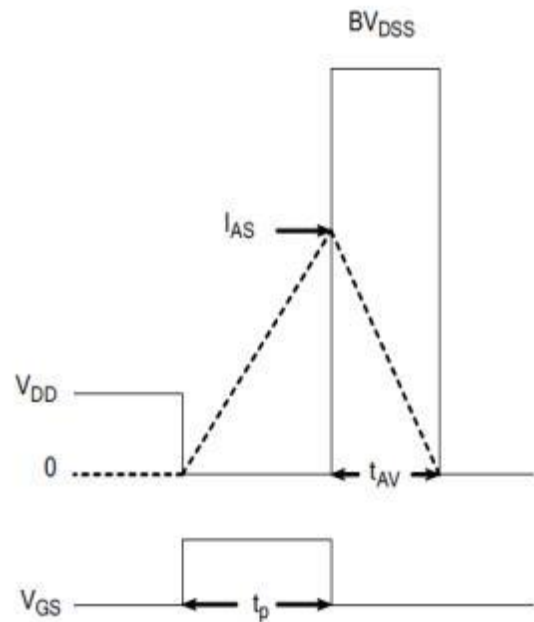


Figure18.Unclamped Inductive Switching Test Circuit

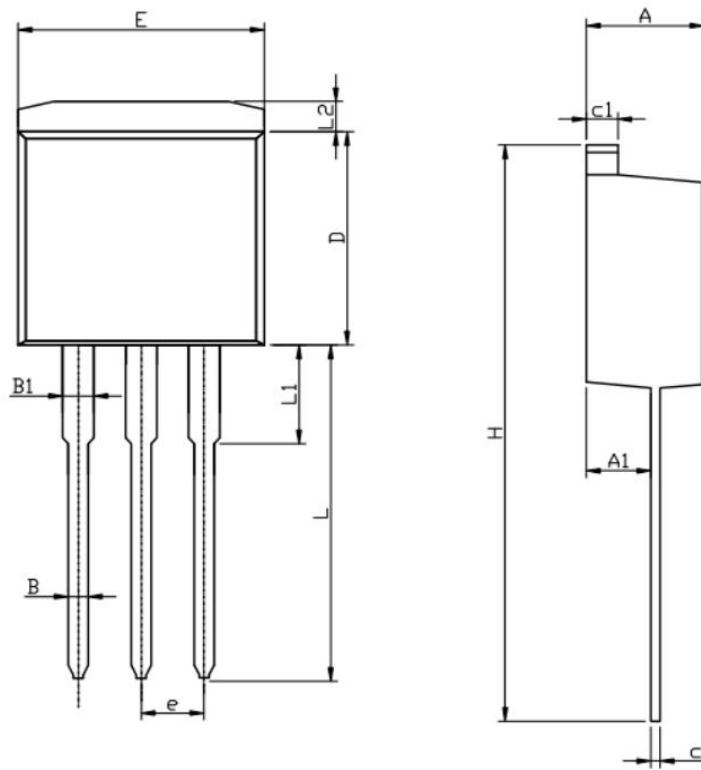


$$E_{AS} = \frac{I_{AS}^2 L}{2}$$

Figure19.Unclamped Inductive Switching Waveforms

Package outline drawing

Unit:mm



Dim.	Min.	Max.
A	4.30	4.55
A1	2.4	2.6
B	0.75	0.85
B1	1.2	1.4
C	0.35	0.42
C1	1.25	1.35
D	8.5	9.5
E	10.15	10.35
H	23	25
L	13	14
L1	2.8	3.5
L2	1.2	1.5
All Dimensions in millimeter		



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